ABSTRACT OF THE DISCLOSURE

MICROELECTRONICS FABRICATION FORMED WITH SPIN-ON PLANARIZING LAYER HAVING A BUCKMINSTERFULLERENE INCORPORATED THEREIN

A method for forming a microelectronics fabrication and a microelectronics fabrication formed in accord with the method. The microelectronics fabrication is formed by providing a substrate employed within a microelectronics fabrication. There is then formed over the substrate a spin-on layer, where the spin-on layer has a buckminsterfullerene incorporated therein. The buckminsterfullerene enhances the planarizing properties of the spin-on layer. The method contemplates a microelectronics fabrication formed in accord with the method.

(FIGURE 2 IS SUGGESTED FOR PUBLICATION)